12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20151215003
Die Conversion for Selected LVC LL Devices in the DBV and DCK Packages
Change Notification / Sample Request

Date: 12/16/2015
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI’s standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20151215003
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G125DCKR	null
SN74LVC1G125DCKT	null
SN74LVC1G126DCKR	null
SN74LVC1G126DCKT	null
SN74LVC1G240DBVR	null
SN74LVC2G06DCKR	null
SN74LVC2G07DBVR	null
SN74LVC2G07DCK3	null
SN74LVC2G07DCKT	null
SN74LVC1G240DCKR	null
SN74LVC2G06DBVR	null
SN74LVC1G126DBVR	null
SN74LVC2G07DCKR	null
SN74LVC1G125DCK3	null
SN74LVC1G11DCKR	null
SN74LVC1G66DCKT	null
SN74LVC1G66DCKR	null
SN74LVC2G17DCKR	null
SN74LVC1G18DCKR	null
SN74LVC1G10DCKR	null
SN74LVC2G17DCKT	null
SN74LVC1G126DBVT	null
SN74LVC1G27DBVR	null
SN74LVC1G332DCKR	null
SN74LVC1G3157DBVR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20151215003	**PCN Date:**	12/16/2015
Title:	Die Conversion for Selected LVC LL Devices in the DBV and DCK Packages		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	3/16/2016	**Estimated Sample Availability:**	Date provided upon sample request

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☒	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

This change notification is to announce a Die Conversion for select LVC LL Devices. The Die Revision will change from A/D/E to revision G. This is a continuation from PCN 20110901001 to backfill the missing devices in the previous PCN. Devices affected by this change are listed in the product affected section of this notification. There will be no change to the data sheet.

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Reliability & electrical characterization evaluation showed no adverse impacts.

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in the table and sample label below:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
A/D/E	**G**

Sample product shipping label to indicate die rev location (**not actual product label**)

TEXAS INSTRUMENTS
G4
MADE IN: Malaysia
2DC:
2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM:
39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV:
(20L) CSO: SHE
(22L) ASO: MLA
(V) 0033317
(21L) CCO:USA
(23L) ACO: MYS

Product Affected:

74LVC1G10DBVRG4	SN74LVC1G11DBVT	SN74LVC1G27DCKR	SN74LVC2G06DCKR
74LVC1G125DCKRE4	SN74LVC1G11DCKJ	SN74LVC1G27DCKRE4	SN74LVC2G06DCKRE4
74LVC1G125DCKRG4	SN74LVC1G11DCKR	SN74LVC1G27DCKRG4	SN74LVC2G06DCKRG4
74LVC1G125DCKTE4	SN74LVC1G11DCKRE4	SN74LVC1G3157DBV3	SN74LVC2G07DBV3
74LVC1G125DCKTG4	SN74LVC1G11DCKRG4	SN74LVC1G3157DBVR	SN74LVC2G07DBVR
74LVC1G126DBVRE4	SN74LVC1G11DCKR-P	SN74LVC1G3157DBVT	SN74LVC2G07DBVRE4
74LVC1G126DBVRG4	SN74LVC1G11DCKT	SN74LVC1G332DBVR	SN74LVC2G07DBVRG4
74LVC1G126DBVTE4	SN74LVC1G125DCK3	SN74LVC1G332DCKR	SN74LVC2G07DBVT
74LVC1G126DBVTG4	SN74LVC1G125DCK3T	SN74LVC1G332DCKRG4	SN74LVC2G07DCK3
74LVC1G126DCKRE4	SN74LVC1G125DCK6	SN74LVC1G386DBVR	SN74LVC2G07DCKJ
74LVC1G126DCKRG4	SN74LVC1G125DCKJ	SN74LVC1G386DCKR	SN74LVC2G07DCKR
74LVC1G126DCKTG4	SN74LVC1G125DCKR	SN74LVC1G66DBVR	SN74LVC2G07DCKRE4
74LVC1G240DBVRE4	SN74LVC1G125DCKR-P	SN74LVC1G66DBVRE4	SN74LVC2G07DCKRG4
74LVC1G240DBVRG4	SN74LVC1G125DCKT	SN74LVC1G66DBVRG4	SN74LVC2G07DCKR-P
74LVC1G240DBVTG4	SN74LVC1G126DBVR	SN74LVC1G66DBVT	SN74LVC2G07DCKR-P3
74LVC1G240DCKRE4	SN74LVC1G126DBVT	SN74LVC1G66DBVTG4	SN74LVC2G07DCKT
74LVC1G240DCKRG4	SN74LVC1G126DCKJ	SN74LVC1G66DCK3	SN74LVC2G07DCKTG4
74LVC1G240DCKTG4	SN74LVC1G126DCKR	SN74LVC1G66DCK3T	SN74LVC2G17DBV3
74LVC1G3157DBVRE4	SN74LVC1G126DCKR-P	SN74LVC1G66DCKJ	SN74LVC2G17DBVR
74LVC1G3157DBVRG4	SN74LVC1G126DCKT	SN74LVC1G66DCKR	SN74LVC2G17DBVRE4
74LVC1G332DBVRG4	SN74LVC1G18DBV3	SN74LVC1G66DCKRE4	SN74LVC2G17DBVRG4
74LVC1G332DCKRE4	SN74LVC1G18DBVR	SN74LVC1G66DCKRG4	SN74LVC2G17DBVR-P
74LVC1G386DCKRG4	SN74LVC1G18DBVRG4	SN74LVC1G66DCKR-P	SN74LVC2G17DBVT
SN74LVC1G10DBVR	SN74LVC1G18DCKR	SN74LVC1G66DCKT	SN74LVC2G17DBVTG4
SN74LVC1G10DBVT	SN74LVC1G18DCKRE4	SN74LVC1G66DCKTG4	SN74LVC2G17DCK3
SN74LVC1G10DCKJ	SN74LVC1G18DCKRG4	SN74LVC1G97DCK3T	SN74LVC2G17DCKJ
SN74LVC1G10DCKR	SN74LVC1G240DBVR	SN74LVC1G97DCKJ	SN74LVC2G17DCKR
SN74LVC1G10DCKRG4	SN74LVC1G240DBVT	SN74LVC1G97DCKR-NG	SN74LVC2G17DCKRE4
SN74LVC1G10DCKT	SN74LVC1G240DCK3T	SN74LVC1G97DCKR-P	SN74LVC2G17DCKRG4
SN74LVC1G11DBVR	SN74LVC1G240DCKR	SN74LVC2G06DBV3	SN74LVC2G17DCKR-P
SN74LVC1G11DBVRE4	SN74LVC1G240DCKT	SN74LVC2G06DBVR	SN74LVC2G17DCKT
SN74LVC1G11DBVRG4	SN74LVC1G27DBVR	SN74LVC2G06DBVRE4	SN74LVC2G17DCKTE4
SN74LVC1G11DBVR-P	SN74LVC1G27DBVRE4	SN74LVC2G06DBVRG4	SN74LVC2G17DCKTG4
SN74LVC1G11DBVR-P3	SN74LVC1G27DBVRG4	SN74LVC2G06DCKJ	

Qualification Data: DCK Devices (Approved 8/04/2011)

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device Construction Details:

Qualification Vehicle #1: SN74LVC1G00DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/T	Wafer Size Dia.	200mm

	iN500		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size(PASS/FAIL)
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
X-Ray	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #2: SN74LVC1G02DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size(PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #3: SN74LVC1G04DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #4: SN74LVC1G06DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #5: SN74LVC1G07DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #6: SN74LVC1G08DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000	Wafer Size Dia.	200mm

	/TiN500		

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #7: SN74LVC1G14DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #8: SN74LVC1G17DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #9: SN74LVC1G32DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #10: SN74LVC1G34DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #11: SN74LVC1G38DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #12: SN74LVC1GU04DCKR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char - LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Approved by A-T Site	PASS

Notes: Qualification tests “pass” on zero fails for each test

Qualification Data: DBV Devices (Approved 8/22/2011)

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device Construction Details:

Qualification Vehicle #1: SN74LVC1G00DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
X-Ray	Approved by A-T Site; Bottom side Only	5/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #2: SN74LVC1G02DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #3: SN74LVC1G04DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #4: SN74LVC1G06DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #5: SN74LVC1G07DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #6: SN74LVC1G08DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #7: SN74LVC1G14DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #8: SN74LVC1G17DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #9: SN74LVC1G32DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #10: SN74LVC1G34DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #11: SN74LVC1G38DBVR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #12: SN74LVC1GU04DBVR			
Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char -LV	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
Notes:	Qualification tests “pass” on zero fails for each test	

Reference Qualification: LVC Little Logic Devices in 6 Pin DSF 1G00/1G02/1G08/1G32/1G38 - HNT

Qualification Data: DSF Devices (Approved 3/30/2011)

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device Construction Details:

Qualification Vehicle #1: SN74LVC1G00DSFR			
Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000/TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
X-Ray	Approved by A-T Site; Bottomside Only	5/0
ESD MM	250V	3/0
ESD HBM	3500V	3/0
Latch Up	JESD 78, Class II	6/0
Steady State Life Test	150C, 300 Hrs	77/0
Manufacturability (assy)		Pass
Notes:	Qualification tests “pass” on zero fails for each test	

Qualification Vehicle #2: SN74LVC1G02DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
Latch-Up	JESD 78, Class II	6/0
ESD MM	200V	3/0
ESD HBM	4000V	3/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #3: SN74LVC1G08DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
ESD MM	200V	3/0
Latch Up	JESD 78, Class II	6/0
ESD HBM	4000V	3/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #4: SN74LVC1G32DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
ESD MM	250V	3/0
ESD HBM	3500V	3/0
Latch Up	JESD 78, Class II	6/0

Notes: Qualification tests "pass" on zero fails for each test

Qualification Vehicle #5: SN74LVC1G38DSFR			
Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
Latch-Up	JESD 78, Class II	6/0
ESD MM	200V	3/0
ESD HBM	4000V	3/0
Notes:	Qualification tests "pass" on zero fails for each test	

Reference Qualification: LVC Little Logic Devices in 6 Pin DSF 1G04/1G06/1G07/1G14/1G17/1G34/1GU04 - HNT

Qualification Data: DSF Devices (Approved 6/27/2011)

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device Construction Details:

Qualification Vehicle #1: SN74LVC1G04DSFR			
Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
X-Ray	Approved by A-T Site; Bottomside Only	5/0
ESD MM	250V	3/0
ESD HBM	5000V	3/0
Latch Up	JESD 78, Class II	6/0
Steady State Life Test	150C, 300 Hrs	77/0
Notes:	Qualification tests "pass" on zero fails for each test	

Qualification Vehicle #2: SN74LVC1G06DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
Latch-Up	JESD 78, Class II	6/0
ESD MM	200V	3/0
ESD HBM	3500V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #3: SN74LVC1G07DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
ESD MM	250V	3/0
Latch Up	JESD 78, Class II	6/0
ESD HBM	4000V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #4: SN74LVC1G14DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
ESD MM	250V	3/0
ESD HBM	4000V	3/0
Latch Up	JESD 78, Class II	6/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #5: SN74LVC1G17DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
Latch-Up	JESD 78, Class II	6/0
ESD MM	250V	3/0
ESD HBM	2000V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #6: SN74LVC1G34DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
ESD MM	250V	3/0
ESD HBM	4000V	3/0
Latch Up	JESD 78, Class II	6/0

Notes: Qualification tests “pass” on zero fails for each test

Qualification Vehicle #7: SN74LVC1GU04DSFR

Wafer Fab Site:	FFAB	Wafer Process:	50b10.13_BOPO2 / P9792
Protective Die Coating:	Ti300/TiN1700/AlCu0.5=6000 /TiN500	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)
Electrical Char	Approved by Product Engineer	PASS
Manufacturability-TQ	Assembly (per mfg. Site specification)	PASS
ESD CDM	1500V	3/0
Latch-Up	JESD 78, Class II	6/0
ESD MM	250V	3/0
ESD HBM	2000V	3/0

Notes: Qualification tests “pass” on zero fails for each test

Reference Qualification: FFAB BOPO2 flows 25b10, 33b10 and 50b10

Qualification Data: Approved 12/11/2008

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device 1: SN74AUC1G08DCK (MSL 1-260C)

Wafer Fab Site:	FFAB	Wafer Process:	25B10/_BOPO2 / D9672
Protective Die Coating:	10KCN	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	**Conditions/Duration**	**Sample Size / Fail**
**Steady State Life Test (HTOL)	150C, 300 Hrs	116/0
**Biased HAST	130C/85%RH/96 Hrs	77/0
**T/C -65C/150C	-65C/+150C (1000 Cyc)	77/0
**Autoclave 121C	121C, 15 PSI (96 Hrs)	77/0
Manufacturability	(per mfg. Site specification)	Pass
Electrical Char		Pass
ESD HBM	2500V	3/0
ESD MM	250V	3/0
ESD CDM	1500V	3/0
Latch-Up	JESD 78, Class II	6/0

** Preconditioning sequence: level 1-260C

Qual Device 2: SN74AVC8T245PW (MSL 1-260C)

Wafer Fab Site:	FFAB	Wafer Process:	33B10 /_BOPO2 / D9722
Protective Die Coating:	10KCN	Wafer Size Dia.	200mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	**Conditions/Duration**	**Sample Size / Fail**
**Steady State Life Test (HTOL)	150C, 300 Hrs	116/0
**Biased HAST	130C/85%RH/96 Hrs	77/0
**T/C -65C/150C	-65C/+150C (1000 Cyc)	76/0
**Autoclave 121C	121C, 15 PSI (96 Hrs)	77/0
Manufacturability	(per mfg. Site specification)	Pass
Electrical Char		Pass
ESD HBM	8000V	3/0
ESD MM	250V	3/0
ESD CDM	2000V	3/0
Latch-Up	JESD 78, Class II	6/0

** Preconditioning sequence: level 1-260C

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com